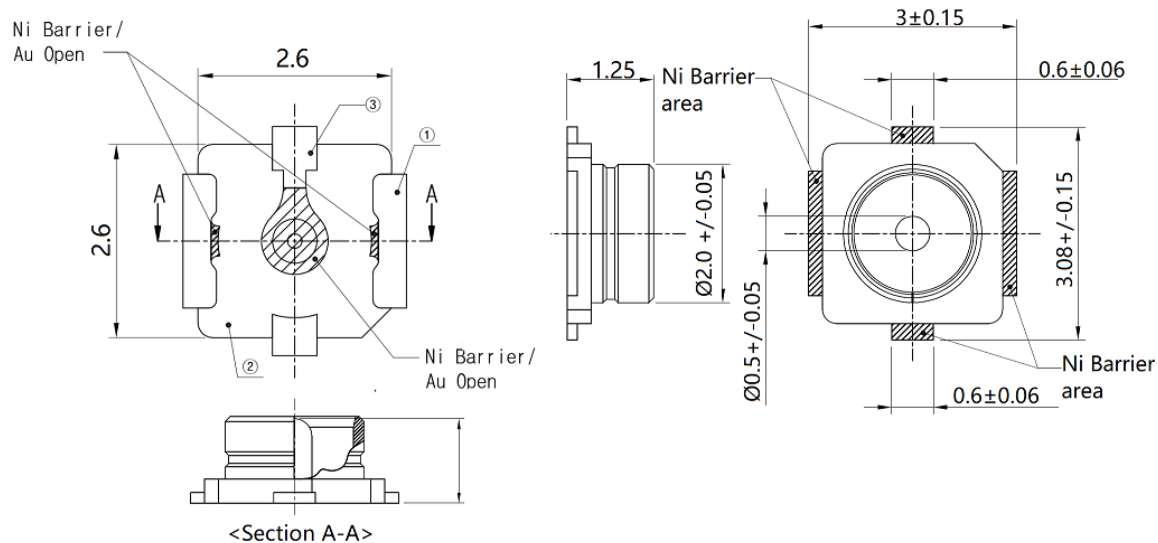


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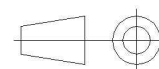
PART NUMBER R302302000



- 1:Body
- 2:Insulator
- 3:Signal Pin(Center contact)

All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
Body	BRONZE	GOLD OVER NICKEL (PCB soldering area)
Center contact	BRASS	GOLD OVER NICKEL (PCB soldering area)
Outer contact		
Insulator	LCP	
Gasket		
Others parts		
-	-	-
-	-	-



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## PACKAGING

Standard	Unit	Other
<b>1000</b>	<b>Contact us</b>	<b>Contact us</b>

## ELECTRICAL CHARACTERISTICS

Impedance		<b>50</b>	Ω
Frequency		<b>0-6</b>	GHz
VSWR	<b>1.35</b>	<b>+</b>	<b>0</b> x F(GHz) Maxi
Insertion loss		<b>NA</b>	√F(GHz) dB Maxi
RF leakage	- (	<b>NA</b>	- F(GHz) dB Maxi
Voltage rating		<b>60</b>	Veff Maxi
Dielectric withstanding voltage		<b>200</b>	Veff mini
Insulation resistance		<b>500</b>	MΩ mini

## MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		<b>NA</b>	N mini
Axial force – Opposite end		<b>NA</b>	N mini
Torque		<b>NA</b>	N.cm mini
Recommended torque			
Mating		<b>NA</b>	N.cm
Panel nut		<b>NA</b>	N.cm
Mating life		<b>30</b>	Cycles mini
Weight		<b>0.02</b>	g

## ENVIRONMENTAL

Operating temperature	<b>-40/+90</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

## SPECIFICATION

## OTHER CHARACTERISTICS

Assembly instruction:

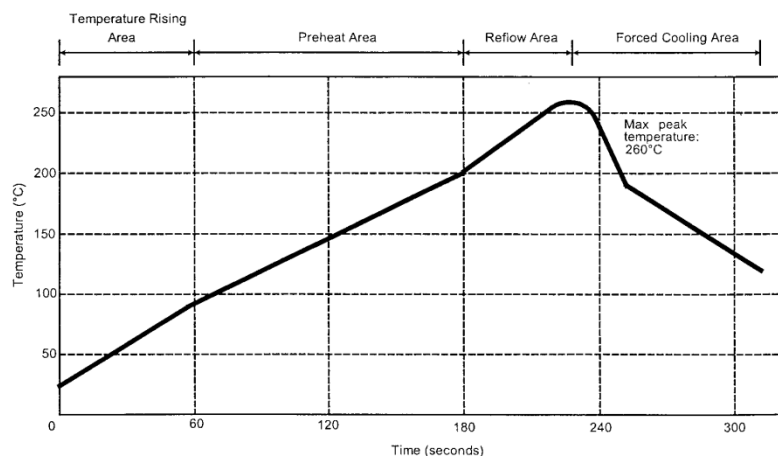
Others:

### SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 microm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component .  
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

**NOTE :** The receptacle and the plug must not be mated before completion of this procedure

### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

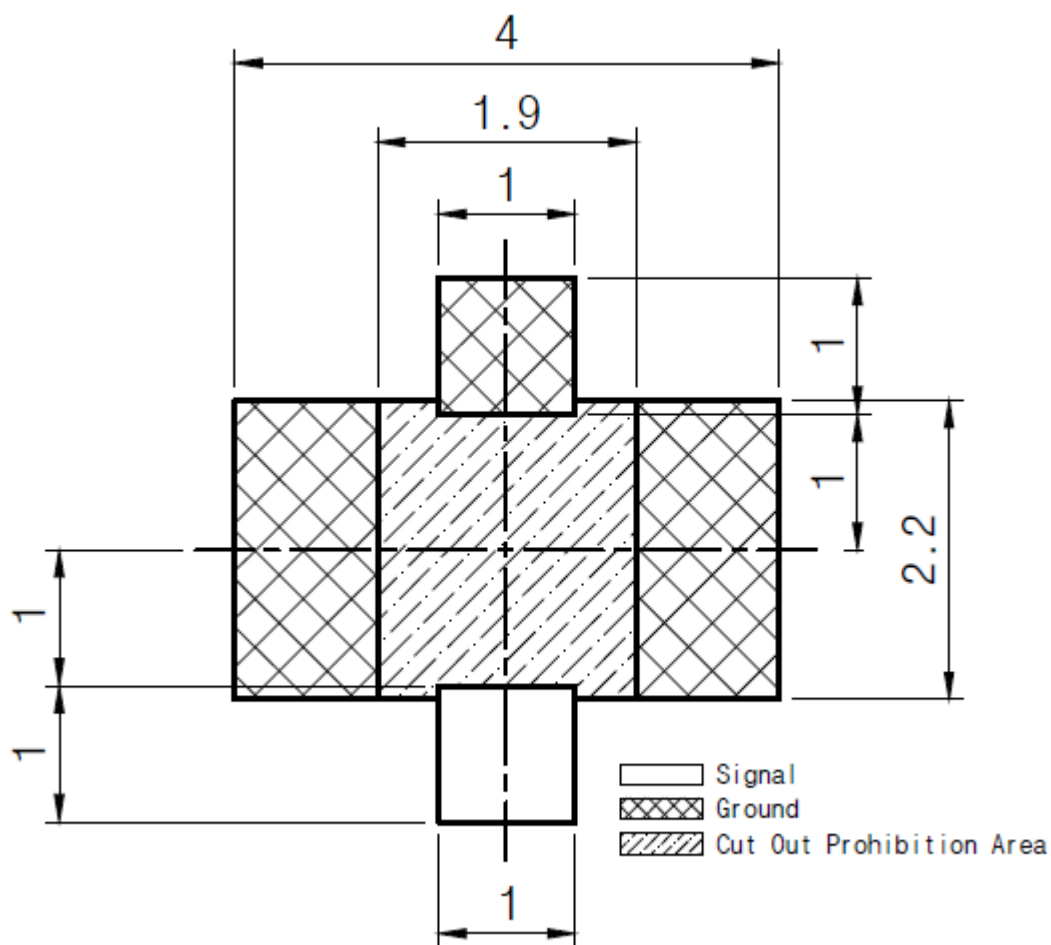
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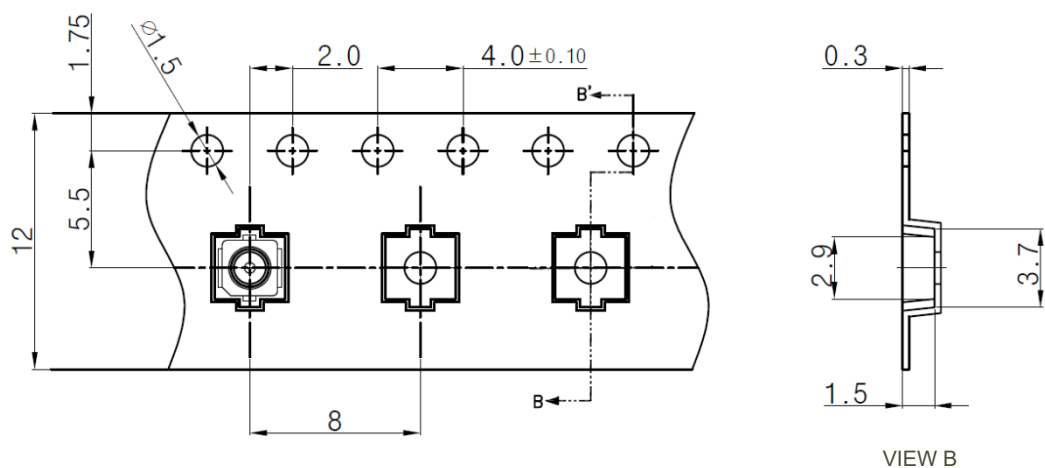
## RECOMMENDED PCB DIMENSIONS



Tolerance:  $\pm 0.05\text{mm}$

## PACKING

### Embossed Taping



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## Reel

